**STEP 1**

Cut rectangular wafers from bulk material using ultrasonic disc cutter

**STEP 2**

Coat all wafers with a thin layer of G-1 & load into Teflon™ mold

**STEP 3**

Cure glued stack under pressure to form a strong bond between wafers.

**STEP 4**

Cut cylinder from stack using ultrasonic disc cutter

Gatan Inc.
Step 1
Mix G-1 epoxy with fibers or powder transfer mixture to a brass tube.

Step 2
Cure epoxy on hot plate for 10 minutes at 130°C.

Step 3
Cut brass tube into disc’s for grinding to required thickness.

Step 4
Disc grind, dimple grind and ion mill to perforation.

Step 5
Glue cylinder inside metal tube. Cure on hot plate.

Step 6
Sliced specimen discs ready for disc grinding and dimpling.

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